

MICROFABRICATED HIGH ASPECT RATIO DEVICE WITH
ELECTRICAL ISOLATION AND INTERCONNECTIONS

Abstract of the Disclosure

A microfabricated device having a high vertical aspect ratio and electrical isolation between a structure region and a circuit region. The device may be fabricated on a single substrate and may include electrical interconnections between the structure region and the circuit region. The device includes a substrate and an isolation trench surrounding a structure region in the substrate. The isolation trench includes a lining of a dielectric insulative material. A plurality of microstructure elements are located in the structure region and are laterally anchored to the isolation trench.

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